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Atty. Docket No.**FIS920020182US1** ET

rd the attached original documents or

To the Honorable Commissioner of Pathopy thereof.

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	2. Name & address of receiving party(ies)
3. Nature of Conveyance: Assignment	Name: Infineon Technologies North America Corp.
Execution Date: 12/06/02	Street Address: 1730 North First Street
	City: San Jose State: CA ZIP: 95112
4. Application number(s) or patent no	umber(s):

Title of Application: A METHOD FOR DEPOSITING A METAL LAYER ON A SEMICONDUCTOR INTERCONNECT STRUCTURE HAVING A CAPPING LAYER

If this document is being filed together with a new application, the execution date of the application is: 12/06/02

A. Patent Application No(s). Docket No. Serial No.	B. Patent No(s)		
lo/318606 Additional number	s attached?Yes X_No		
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: <u>1</u>		
Name: Ira David Blecker 32074 Street Address: IBM Corporation	7. Total fee (37 CFR 3.41): \$40.00 Enclosed _X_ Authorized to be charged to deposit account		
Intellectual Property Law Dept. Dept. 18G/Bldg. 300-482 2070 Route 52 Hopewell Junction, NY 12533-6531	8. Deposit A/C no.: 09-0458 (FI-565) (Attach duplicate copy of this page if paying by deposit account)		

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9. Statement of signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ira D. Blecker, Reg.# 29,894 Name of Person Signing Telephone No. (845) 894-2580

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<u><u><u>Jlc.11</u></u> Date</u>

Total number of pages, including cover sheet, attachments, and document _2

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: UNITED STATES PATENT AND TRADEMARK OFFICE, PO BOX 2327, ARLINGTON, VA 22202. Applicant and/or Attorney requests the date of deposition in the former of the position of the po

REEL: 013594 FRAME: 0442

ASSIGNMENT

WHEREAS, I

(1) Mark Hoinkis of 37 Spruce Ridge Drive, Fishkill, New York 12524, USA

has invented certain improvements in

A METHOD FOR DEPOSITING A METAL LAYER ON A SEMICONDUCTOR INTERCONNECT STRUCTURE HAVING A CAPPING LAYER

and executed a United States patent application therefor on:

(1) DEC OZ, 2002 (date that Inventor(s) signed the declaration)

Whereas, INFINEON TECHNOLOGIES NORTH AMERICA CORP., having a place of business at San Jose, California 95112, (hereinafter called Assignee), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign and transfer to Assignee, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to Assignee, its successors and assigns; and I hereby agree that Assignee may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by Assignee.

Signed

at East Fishkill, NY Mark Homikie on <u>GPEC. 02</u>, 2002, Mark Hoinkis

PATENT Page 1 of 1 REEL: 013594 FRAME: 0443

RECORDED: 12/11/2002